

AMENDMENTS TO THE SPECIFICATION:

Please delete the paragraphs on page 12, lines 2-11, and substitute therefor the following new paragraphs:

--FIGS. 30A to FIG. 30C are general plan views showing an example of photomasks used to manufacture the semiconductor integrated circuit device of FIG. 29, namely, FIG. 30A shows an IP mask used in transferring a pattern of a memory mat, FIG. 30B shows an IP mask used in transferring a pattern of a peripheral circuit region, and FIG. 30C shows an IP mask used in transferring a pattern of a peripheral circuit region; and

FIG. 31 is a general plan view showing an example of a photomask under fabrication used to manufacture the semiconductor integrated circuit device of FIG. 29; and

FIG. 32 shows an example of a product mask manufactured using the IP masks Mm20 to Mm22 shown in FIGS. 30A to 30C.--